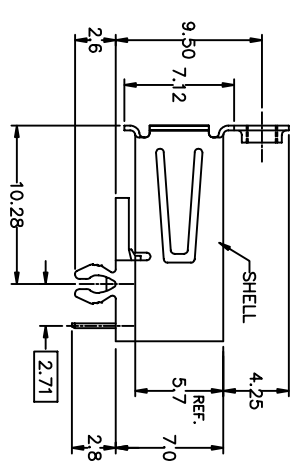
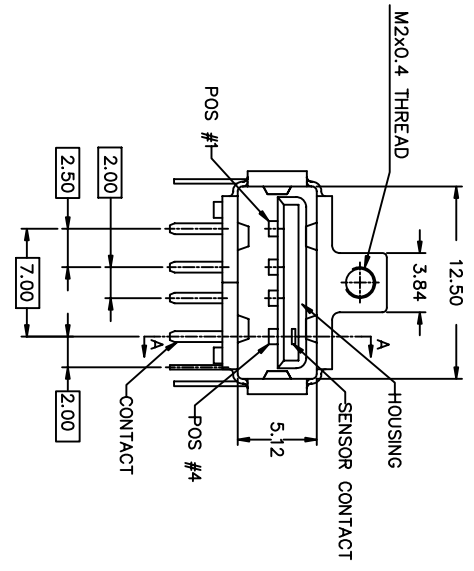
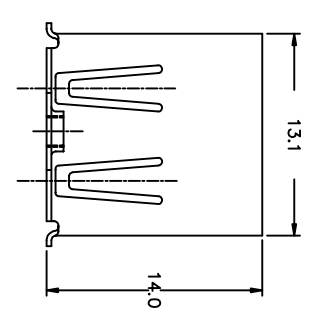
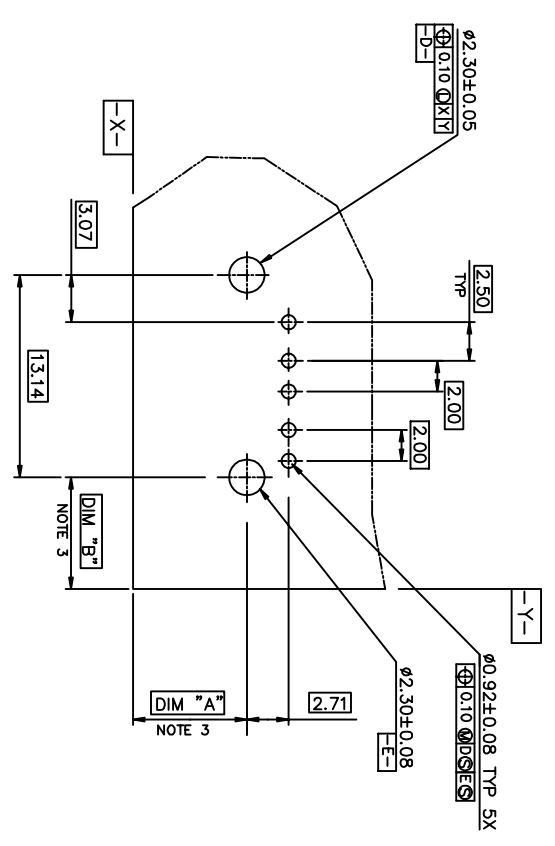


PRODUCT NO.
SEE SHEET 3



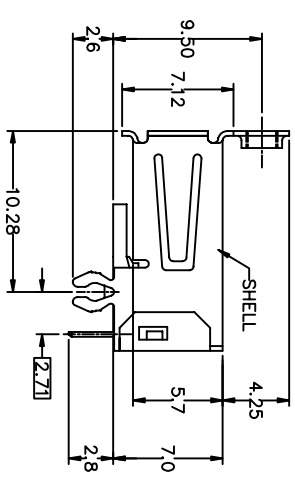
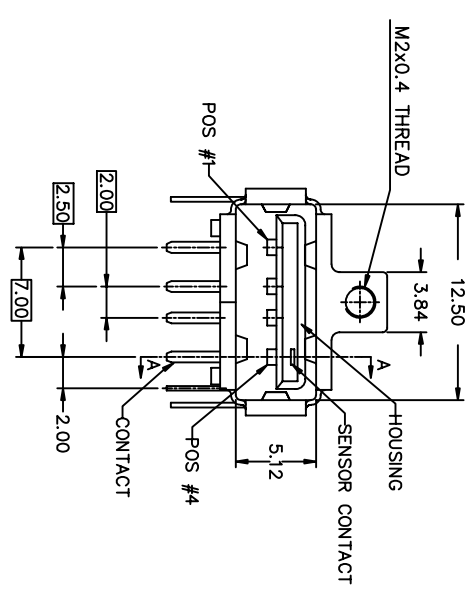
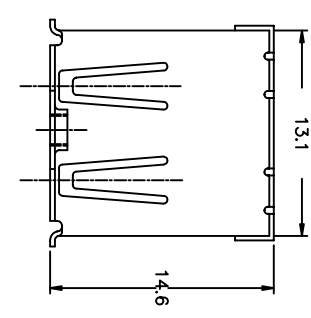
ASSEMBLY WITHOUT BACK SHIELD



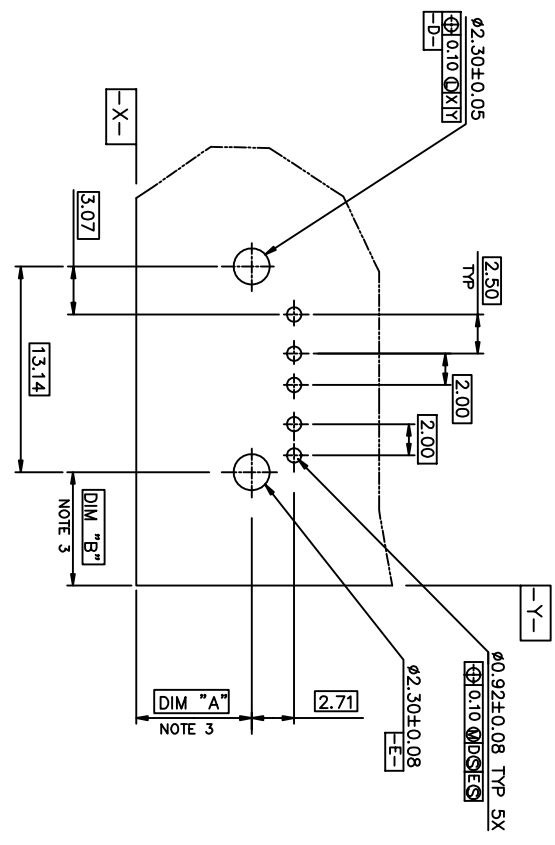
P.C. BOARD LAYOUT

rev.	ecsn no.	dr.	date	linear	tolerance unless otherwise specified	CUSTOMER COPY	projection	title	product family	size	dwg no.	code	sheet
A	T70233	P P	6/18/97	.00 ± 0.30				UNIVERSAL BUS RECEPTACLE-CATALOG	USB	A3	61819		1 OF 3
B	T70333	C L	08/11/97	.0002 ± 0.10									
C	T04-0208	W L	05/13/04	± 3									
D	N04-0123	PH	12/13/04	dr									
E	N06-0101	HB	04/13/08	angr									
		chr	R Y LUU	07/10/97	scale	Z:5:1							
		oppd	JENN TSAO	07/10/97									

PRODUCT NO.
 SEE SHEET 3



ASSEMBLY WITH BACK SHIELD



P.C. BOARD LAYOUT

mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		title	
rev.	ecn no.	dr	date	linear	projection	UNIV SERIAL BUS S.M.T.	
B				.00 ± 0.20	AS	RECEPTACLE-CATALOG	
				.000 ± 0.10		Product family USB	
				± .3°		dwg no. 61819	
				dir SHIPLEY HSD/01/10/97	unit mm/inch	code	
				engr R Y LIU 01/10/97	size	sheet	
				chr R Y LIU 01/10/97	scale 2.5:1	2 OF	
				pppd JENN TSAO/01/10/97			
sheet revision							
index	sheet						

PRODUCT NUMBER CODE

61819 - X X X X X S LF

BASE PRODUCT NUMBER

HOUSING COLOR OPTIONS

- 0 - WHITE
- 1 - BLACK

PIN NO. OPTION

- 0 - 5 PIN
- 1 - 4 PIN

SHELL OPTIONS

- 1 - WITHOUT BACK SHIELD
- 2 - WITH BACK SHIELD

TERMINAL PLATING OPTION

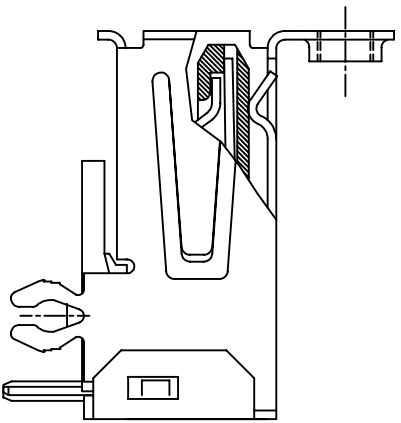
- 0 - 50u" Ni UNDERPLATE
- 30u" GXT CONTACT AREA
- 100u" TIN/LEAD TAIL AREA
- 1 - 50u" Ni UNDERPLATE
- 30u" GXT CONTACT AREA
- 100u" TIN TAIL AREA

PACKAGING OPTION

- B - TUBES

ONLY FOR PANASONIC

LEAD FREE OPTION
 WHEN "TERMINAL PLATING OPTION" IS 1



NOTES:

1. MATERIAL: PHOSPHOR BRONZE
 CONTACTS: PHOSPHOR BRONZE
 SHIELD: PHOSPHOR BRONZE
 HOUSING: UL 94V-0 THERMOPLASTIC, COLOR: WHITE
2. PLATING: CONTACTS: GOLD FLASH OVER
 PALLADIUM NICKEL (0.76um MINIMUM) IN CONTACT
 AREA; 2.54 um TIN-LEAD OR TIN MINIMUM IN SOLDER TAIL AREA.
 1.27 um MINIMUM NICKEL UNDERPLATE OVER ALL SURFACES.
 SHIELD: 2.54 um MINIMUM TIN/LEAD OR TIN OVER 1.27 um
 MINIMUM NICKEL UNDERPLATE
3. DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER.
4. RECOMMENDED BOARD THICKNESS IS 0.8~1.2 mm.
5. MAXIMUM PANEL THICKNESS TO BE 2.67 mm IF MOUNTED
 BEHIND PANEL.
6. PACKING STANDARD GS-14-920 WILL BE APPLIED FOR LEAD
 FREE P/N'S
7. FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION
 DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN
 GS-22-008
8. FOR LEAD FREE P/N'S, THE HOUSING WILL WITHSTAND EXPOSURE
 TO 260°C PEAK TEMPERATURE FOR 40 SECONDS IN A CONVECTION,
 INFRO-RED OR VAPOR PHASE REFLOW OVEN.

mat'l code	tolerance unless otherwise specified	CUSTOMER COPY	projection	title	product family	code
rev. econ no. dr.	date					
E	linear 0 ± 0.30 .00 ± 0.20 .000 ± 0.10			UNIVERSAL BUS RECEPTACLE	61819	3 OF
	angles ± .3°					
	ShIPLEY HSU 01/10/97					
	engr R Y LUU 01/10/97					
	chr R Y LUU 01/10/97					
	qppd JENN TSAO 01/10/97					
sheet revision						
index sheet						